

- ◆ N-Channel Power MOS FET
- ◆ DMOS Structure
- ◆ Low On-State Resistance:  $0.045\Omega$  MAX
- ◆ Ultra High-Speed Switching
- ◆ SOP-8 Package

### ■ Applications

- Notebook PCs
- Cellular and portable phones
- On-board power supplies
- Li-ion battery systems

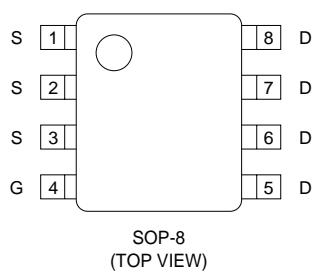
### ■ General Description

The XP131A1145SR is a N-Channel Power MOS FET with low on-state resistance and ultra high-speed switching characteristics. Because high-speed switching is possible, the IC can be efficiently set thereby saving energy. The small SOP-8 package makes high density mounting possible.

### ■ Features

- Low on-state resistance:**  $R_{ds(on)}=0.03\Omega(V_{gs}=10V)$   
 $R_{ds(on)}=0.045\Omega(V_{gs}=4.5V)$
- Ultra high-speed switching**  
**Operational Voltage:** 4.5V  
**High density mounting:** SOP-8

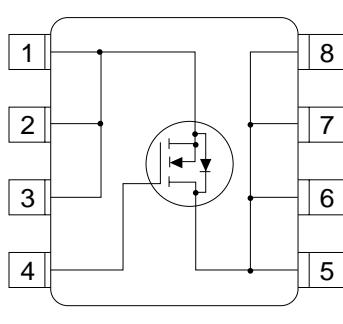
### ■ Pin Configuration



### ■ Pin Assignment

PIN NUMBER	PIN NAME	FUNCTION
1~3	S	Source
4	G	Gate
5~8	D	Drain

### ■ Equivalent Circuit



### ■ Absolute Maximum Ratings

Ta=25°C

PARAMETER	SYMBOL	RATINGS	UNITS
Drain-Source Voltage	Vdss	30	V
Gate-Source Voltage	Vgss	$\pm 20$	V
Drain Current (DC)	Id	7	A
Drain Current (Pulse)	Idp	30	A
Reverse Drain Current	ldr	7	A
Continuous Channel Power Dissipation (note)	Pd	2.5	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55~150	°C

Note: When implemented on a glass epoxy PCB

## ■ Electrical Characteristics

### DC characteristics

Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Drain Cut-off Current	Idss	Vds=30V, Vgs=0V			10	µA
Gate-Source Leakage Current	Igss	Vgs=±20V, Vds=0V			±1	µA
Gate-Source Cut-off Voltage	Vgs(off)	Id=1mA, Vds=10V	1.0		2.5	V
Drain-Source On-state Resistance (note)	Rds(on)	Id=4A, Vgs=10V		0.025	0.03	Ω
		Id=4A, Vgs=4.5V		0.035	0.045	Ω
Forward Transfer Admittance (note)	Yfs	Id=4A, Vds=10V		14		S
Body Drain Diode Forward Voltage	Vf	If=7A, Vgs=0V		0.85	1.1	V

Note: Effective during pulse test.

### Dynamic characteristics

Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Capacitance	Ciss	Vds=10V, Vgs=0V f=1MHz		620		pF
Output Capacitance	Coss			350		pF
Feedback Capacitance	Crss			120		pF

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### Switching characteristics

Ta=25°C

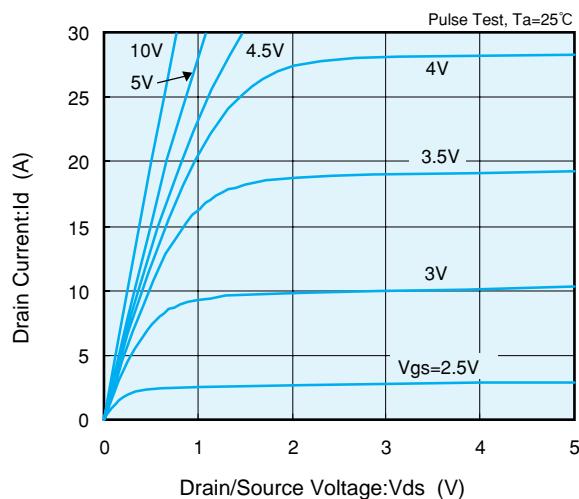
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Turn-on Delay Time	td (on)	Vgs=5V, Id=4A Vdd=10V		15		ns
Rise Time	tr			20		ns
Turn-off Delay Time	td (off)			30		ns
Fall Time	tf			10		ns

### Thermal characteristics

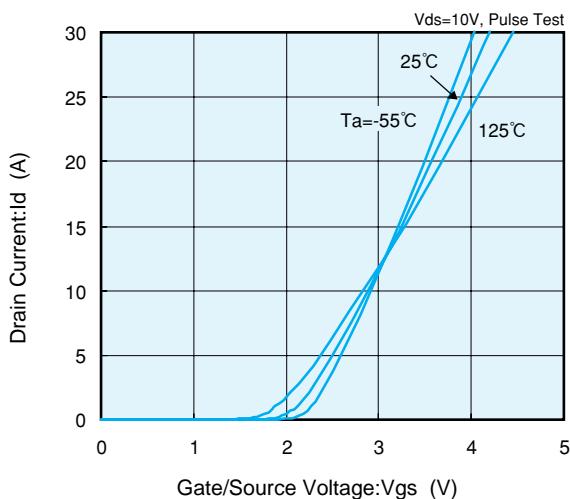
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Thermal Resistance (channel-surroundings)	Rth (ch-a)	Implement on a glass epoxy resin PCB		50		°C/W

## ■ Electrical Characteristics

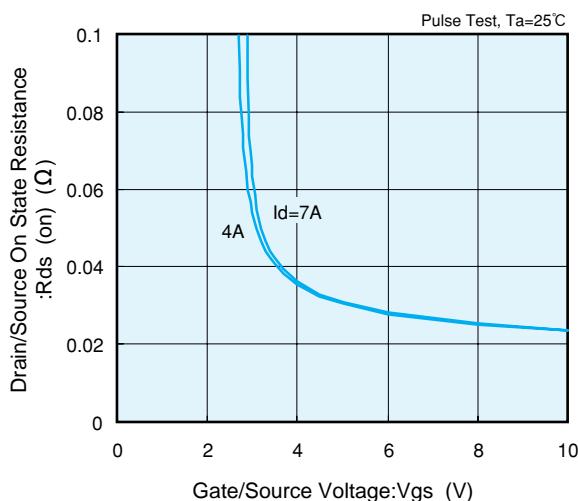
Drain Current vs. Drain/Source Voltage



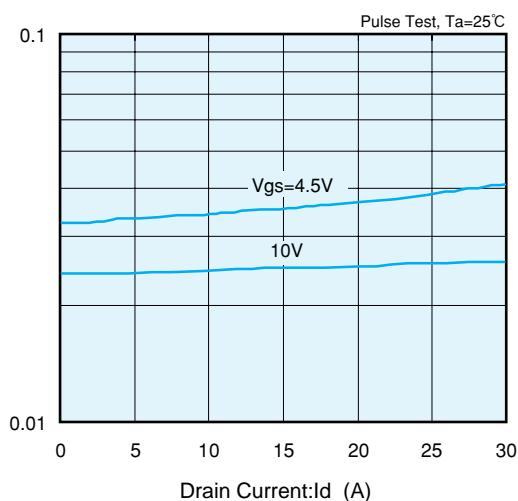
Drain Current vs. Gate/Source Voltage



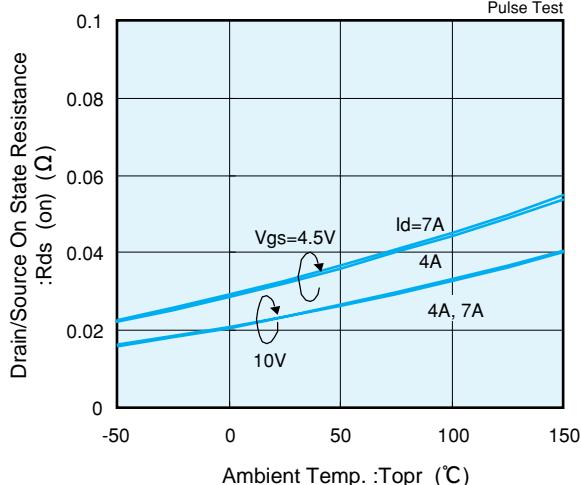
Drain/Source On-State Resistance vs. Gate/Source Voltage



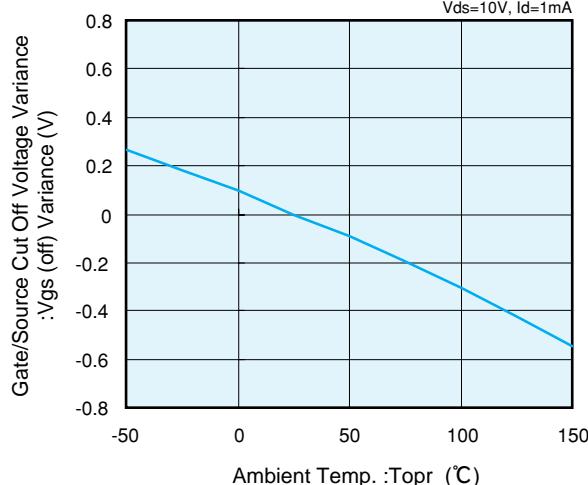
Drain/Source On-State Resistance vs. Drain Current



Drain/Source On-State Resistance vs. Ambient Temperature

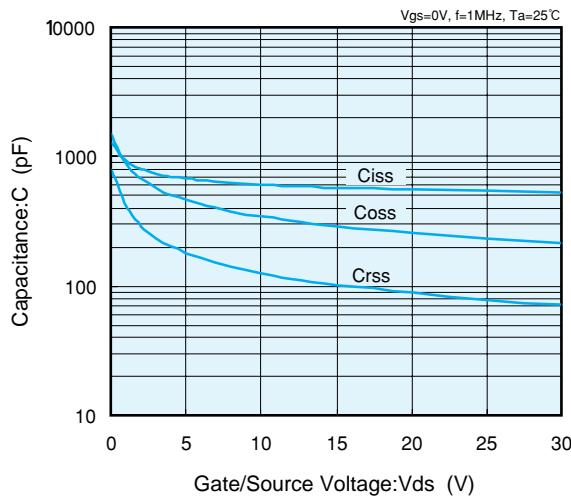


Gate/Source Cut-Off Voltage Variance vs. Ambient Temperature

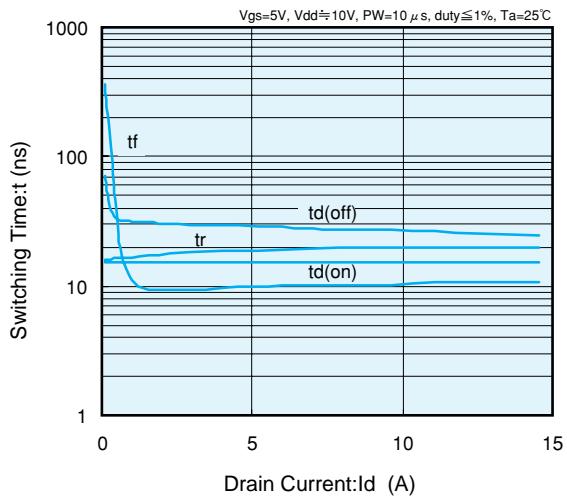


## ■ Electrical Characteristics

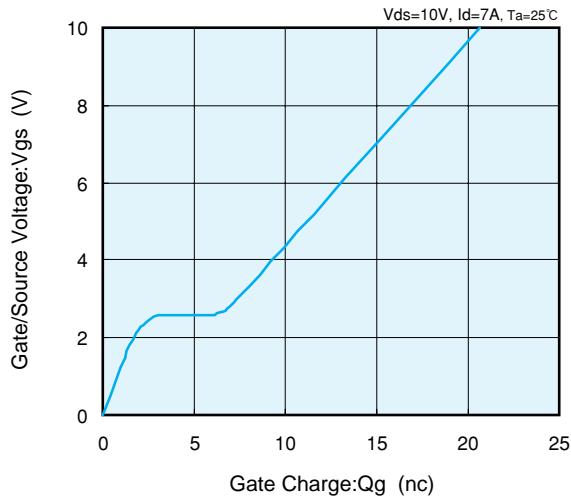
Drain/Source Voltage vs. Capacitance



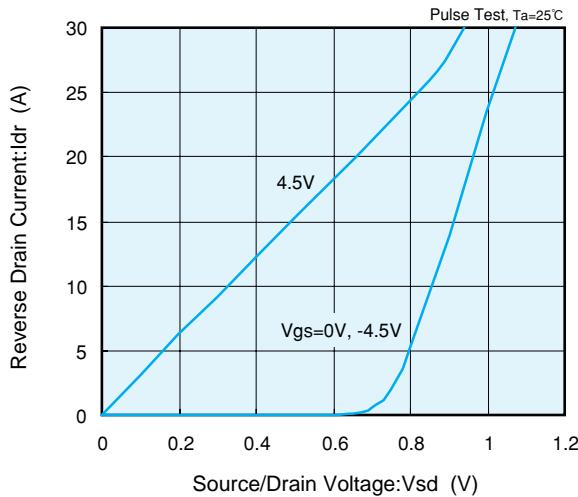
Switching Time vs. Drain Current



Gate/Source Voltage vs. Gate Charge



Reverse Drain Current vs. Source/Drain Voltage



Standardized Transition Thermal Resistance vs. Pulse Width

